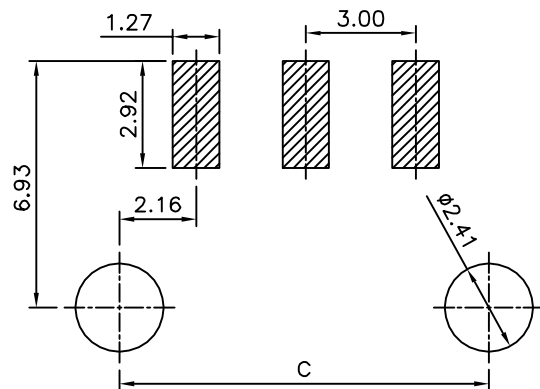
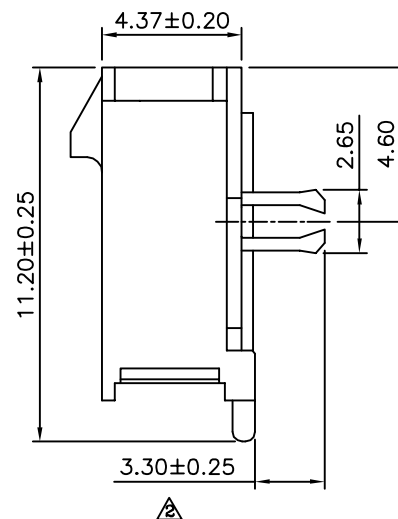
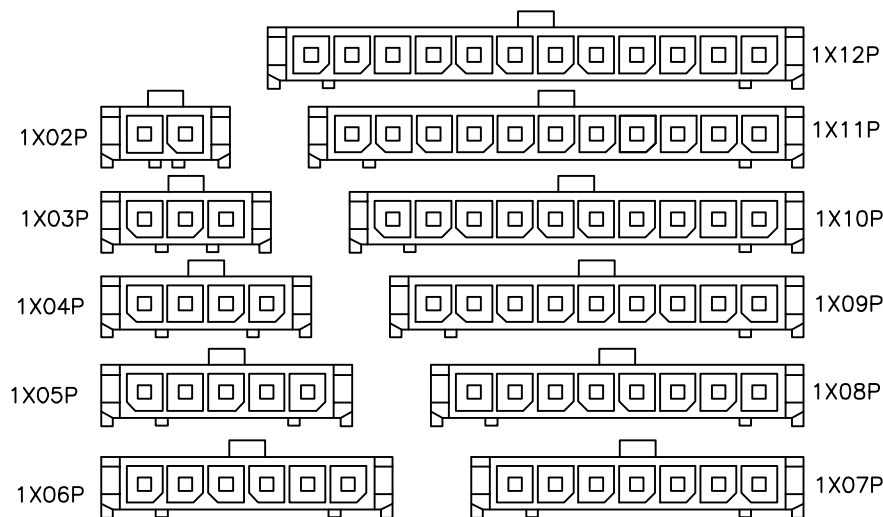
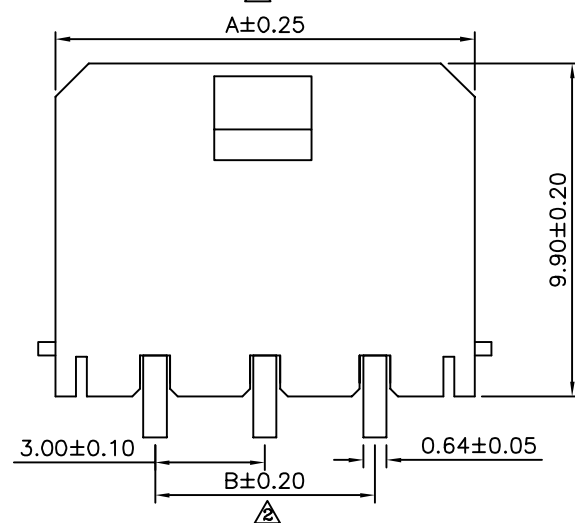
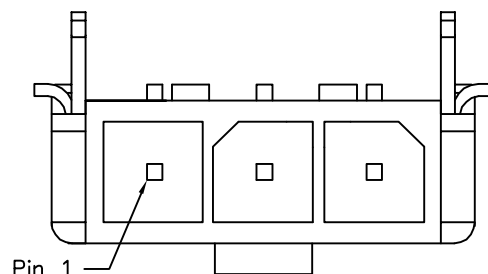


SPECIFICATION
1.General Characteristics
 3.0mm Micro-Fit Wafer 1XXX SMT 90°
 With DIP Boardlock Black Insulator
 Tin Plated Tape & Reel 250 PCS/Reel
2.Material&Finish
 Insulator:LCP(UL94V-0),Black
 Contact:Brass,Tin Plated
 Solder Tabs:Brass,Tin Plated
3.Electrical Characteristics
 Current Rating:5A AC,DC
 Voltage Rating:250V AC,DC
 Withstanding Voltage:1500V AC/Minute
 Insulation Resistance:1000 Megaohms Min.
 Contact Resistance:20 Milliohms Max.
4.Environmental Characteristics
 Temperature Range:-25°C~+85°C
5.RoHS Compliant



Recommended P.C.B. Layout



Pin	A	B	C
02	9.65	3.00	7.30
03	12.65	6.00	10.30
04	15.65	9.00	13.30
05	18.65	12.00	16.30
06	21.65	15.00	19.30
07	24.65	18.00	22.30
08	27.65	21.00	25.30
09	30.65	24.00	28.30
10	33.65	27.00	31.30
11	36.65	30.00	34.30
12	39.65	33.00	37.30

4UCON 元化興業股份有限公司
 4UCON TECHNOLOGY INC.

DRAWING No.

21197

APPROVED BY

MEI

CHECKED BY

HZF

DRAWING BY

CYP

UNLESS OTHERWISE
 SPECIFIED
 TOLERANCES ARE

X₁ ±0.30
 X₂ ±0.25
 X₃ ±0.20
 XXX ±0.05
 ANG. ±1°

SCALE

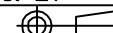
NONE

REV.

A2

UNIT

mm



NO.	REV.	REVISIONS	CHK	DATE
A2		Modify Data	HZF	03/23/2016
A1		Modify P/N:MIF1XXXPWZ-H --> MIF1XXXPWZ-R2H5-H	HZF	12/08/2014
A0		NEW RELEASE	HZF	08/02/2012